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Lei et al.(10) **Pub. No.: US 2024/0223139 A1**(43) **Pub. Date: Jul. 4, 2024**(54) **RADIO FREQUENCY MODULE**(71) Applicant: **RADROCK (SHENZHEN)**
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ABSTRACT

Disclosed is an RF module. The substrate includes a first layout area and a second layout area. The first RF chip is located in the first layout area, including a first power amplifier and a second power amplifier. The first switch chip is arranged in the first layout area and connected to the output ends of the first and second power amplifier. The second RF chip is arranged in second layout area, including a third power amplifier. The second switch chip is arranged in the second layout area and connected to the output end of the third power amplifier. The RF module shortens the transmission distance of RF signals between the first RF chip and first switch chip and between the second RF chip and second switch chip by arranging components in two areas separately, thus reducing the insertion loss and interference and improving the output quality of RF signals.

